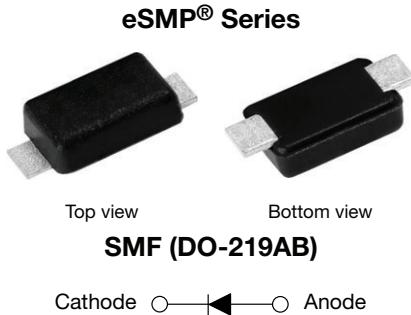


# Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifiers



## LINKS TO ADDITIONAL RESOURCES


[3D Models](#)

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	3.0 A
$V_{RRM}$	100 V
$I_{FSM}$	55 A
$V_F$ at $I_F = 3$ A ( $T_A = 125$ °C)	0.62 V
$T_J$ max.	175 °C
Package	SMF (DO-219AB)
Circuit configuration	Single

## FEATURES

- Trench MOS Schottky technology
- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Compatible to SOD-123W package case outline
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT  
HALOGEN  
FREE

## TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

## MECHANICAL DATA

### Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, RoHS-compliant  
Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** color band denotes the cathode end

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	V3FM10	UNIT
Device marking code		3MB	
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	V
Maximum average forward rectified current (fig.1)	$I_{F(AV)}^{(1)}$	2.5	A
	$I_{F(AV)}^{(2)}$	3.0	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	55	A
Operating junction temperature range	$T_J$ <sup>(3)</sup>	-40 to +175	°C
Storage temperature range	$T_{STG}$	-55 to +175	

### Notes

- (1) Free air, mounted on FR4 PCB, 2 oz. standard footprint
- (2) Mounted on FR4 PCB, 2 oz. 10 mm x 10 mm copper pad areas
- (3) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT	
Instantaneous forward voltage	$I_F = 1.5 \text{ A}$	$T_A = 25^\circ\text{C}$	$V_F$ <sup>(1)</sup>	0.59	-	V	
	$I_F = 3.0 \text{ A}$			0.74	0.83		
	$I_F = 1.5 \text{ A}$	$T_A = 125^\circ\text{C}$		0.52	-		
	$I_F = 3.0 \text{ A}$			0.62	0.70		
Reverse current	$V_R = 70 \text{ V}$	$T_A = 25^\circ\text{C}$	$I_R$ <sup>(2)</sup>	0.7	-	$\mu\text{A}$	
		$T_A = 125^\circ\text{C}$		500	-		
	$V_R = 100 \text{ V}$	$T_A = 25^\circ\text{C}$		-	85		
		$T_A = 125^\circ\text{C}$		900	3000		
Typical junction capacitance	$4.0 \text{ V}, 1 \text{ MHz}$		$C_J$	240	-	pF	

**Notes**

(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle

(2) Pulse test: Pulse width  $\leq 5 \text{ ms}$

**THERMAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	V3FM10	UNIT
Typical thermal resistance	$R_{\theta JA}$ <sup>(1)(2)</sup>	125	$^\circ\text{C/W}$
	$R_{\theta JM}$ <sup>(3)</sup>	22	

**Notes**

(1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

(2) Device mounted on FR4 PCB, 2 oz. standard footprint, thermal resistance  $R_{\theta JA}$  – junction-to-ambient

(3) Device mounted on 10 mm x 10 mm pad size area footprint; thermal resistance  $R_{\theta JM}$  – junction-to-mount

**ORDERING INFORMATION** (Example)

PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V3FM10-M3/H	0.015	H	3000	7" diameter plastic tape and reel
V3FM10-M3/I	0.015	I	10 000	13" diameter plastic tape and reel
V3FM10HM3/H <sup>(1)</sup>	0.015	H	3000	7" diameter plastic tape and reel
V3FM10HM3/I <sup>(1)</sup>	0.015	I	10 000	13" diameter plastic tape and reel

**Note**

(1) AEC-Q101 qualified

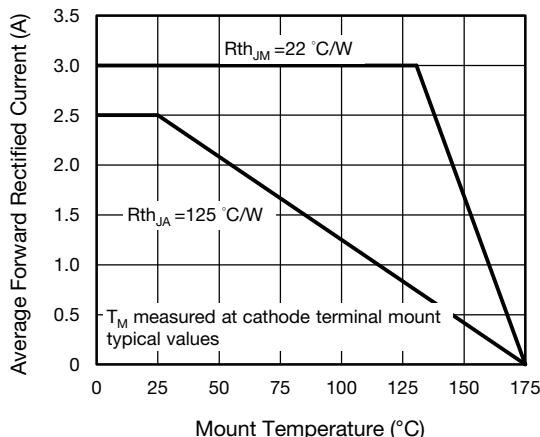
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

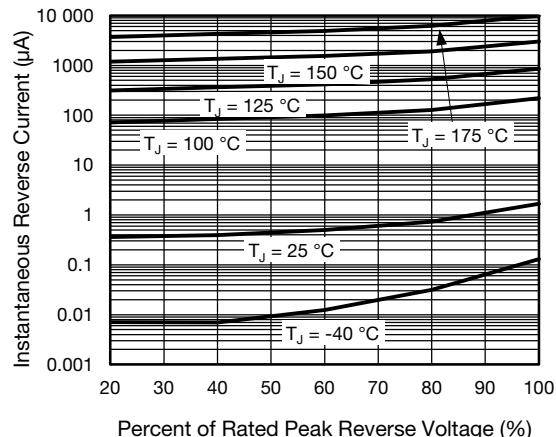


Fig. 4 - Typical Reverse Leakage Characteristics

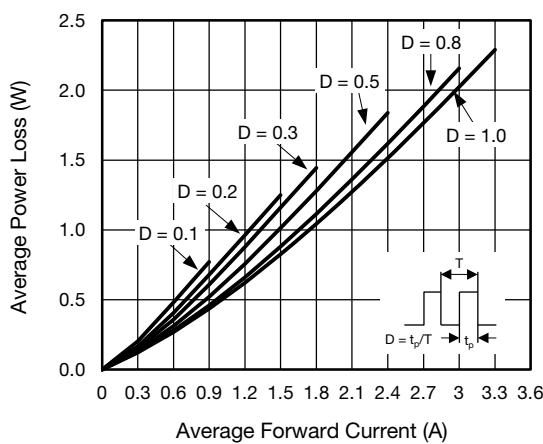


Fig. 2 - Average Power Loss Characteristics

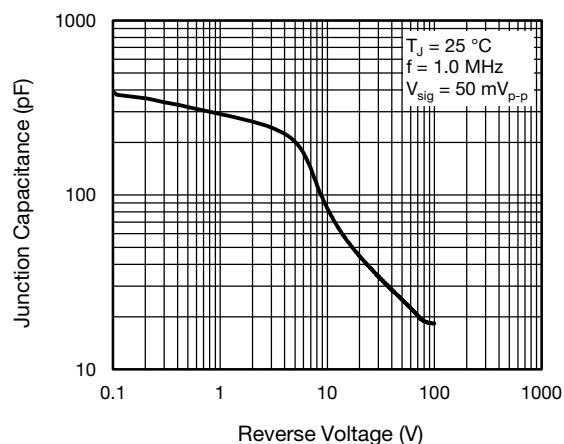


Fig. 5 - Typical Junction Capacitance

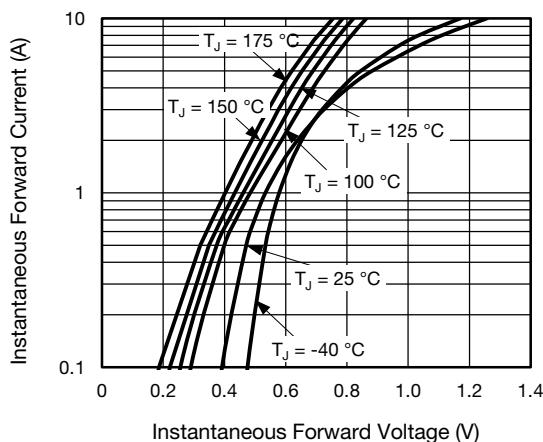


Fig. 3 - Typical Instantaneous Forward Characteristics

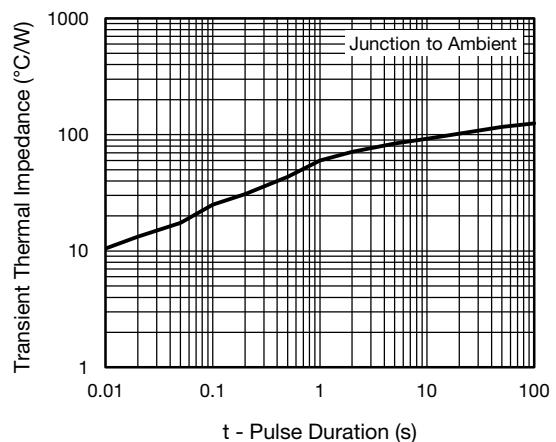
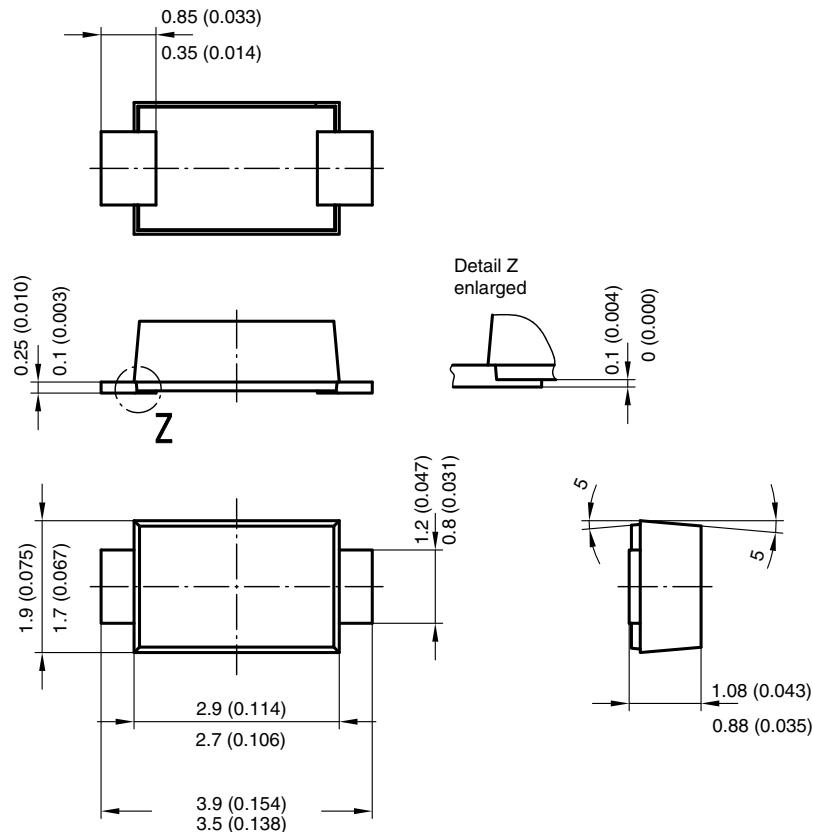
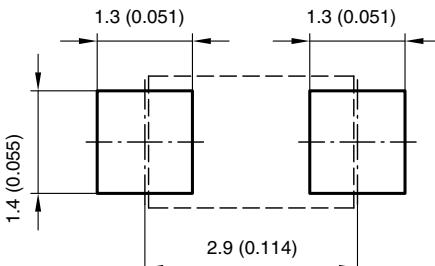


Fig. 6 - Typical Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in millimeters (inches)


Foot print recommendation:



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